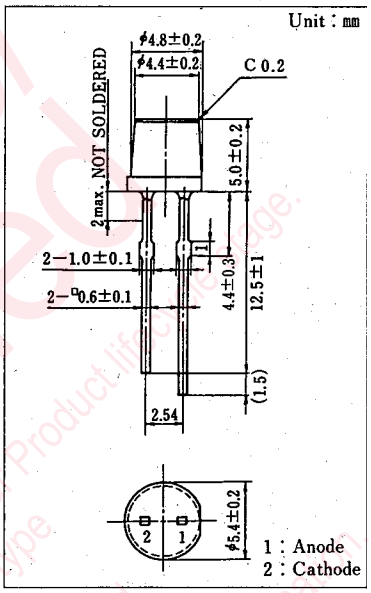
LN64

GaAs Infrared Light Emitting Diode

For Optical Control Systems



■ Features

- High-power output: P_O=7mW (typ.)
- Suited for use with silicon photo detectors
- Good linearity (P_O vs I_F)
- Wide beam angle: θ=45 deg. (typ.)
- Transparent epoxy package

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Power Dissipation	P_D	160	mW
Forward Current (DC)	I_F	100	mA
Pulse Forward Current	I_{FP} *	1.5	A
Reverse Voltage (DC)	V_R	3	V
Operating Ambient Temperature	T_{opr}	−25～+85	℃
Storage Temperature	T_{stg}	−40～+100	℃

* f=100Hz, Duty Cycle=0.1%

■ Electro-Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Optical Power Output	P_O	I_F=50mA	3.5	7		mW
Peak Emission Wavelength	λ_P	I_F=50mA		950		nm
Spectral Band Width	$\Delta\lambda$	I_F=50mA		50		nm
Forward Voltage (DC)	V_F	I_F=100mA		1.3	1.6	V
Reverse Current (DC)	I_R	V_R=3V			10	μA
Capacitance between Terminals	C_t	V_R=0, f=1MHz		35		pF
Beam Half Angle	θ	Measured from the optical axis to the half power point		45		deg.

Maintenance/ Discontinued
Maintenance includes following our Product lifecycle.
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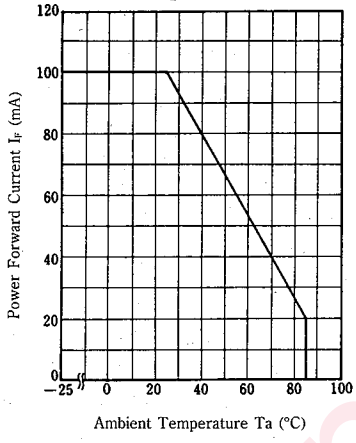
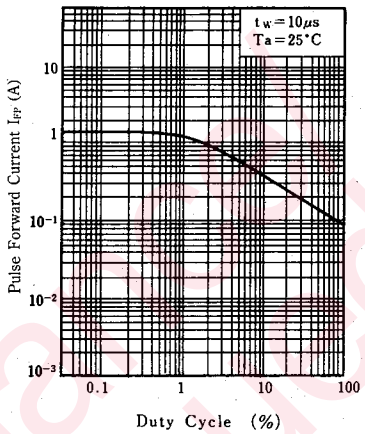
discontinued type
Please refer following URL about latest information
http://www.semicon.panasonic.co.jp/en

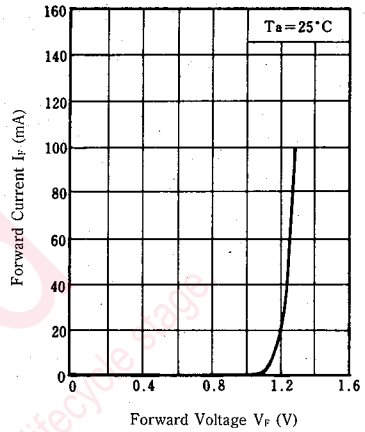
$I_F - Ta$



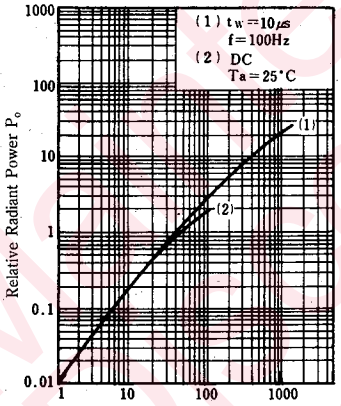
$I_{FP} - Duty\ Cycle$



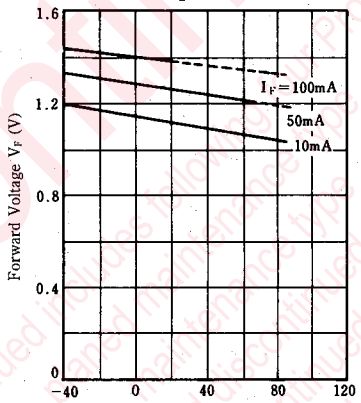
$I_F - V_F$



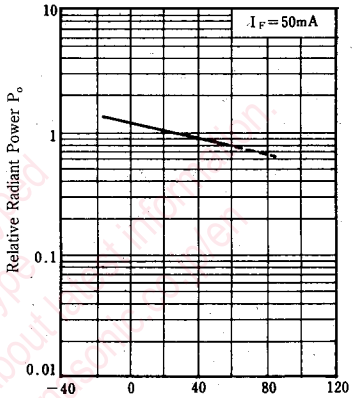
$P_O - I_{FP}$



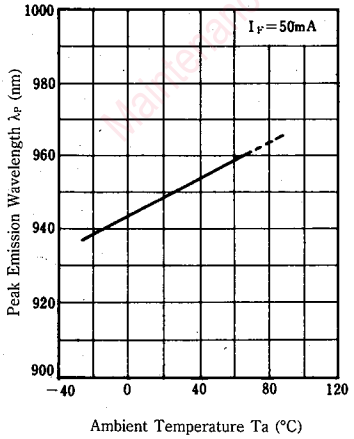
$V_F - Ta$



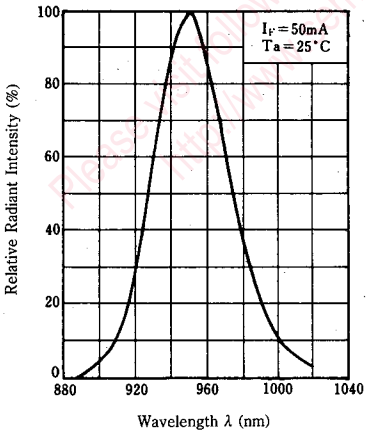
$P_O - Ta$



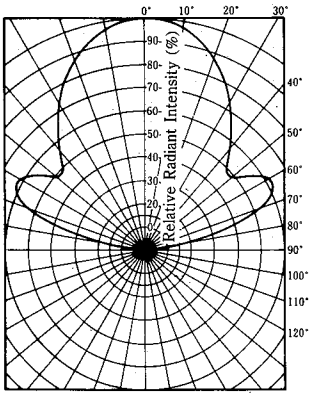
$\lambda_P - Ta$



Spectral Characteristics



Directional Characteristics



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